			,
CERTIFICATE OF TO Applicant(s): Darbha et al.	RANSMISSION BY FAC	SIMILE (37 CFR 1.8)	Docket No. END920010115US2
Application No. 10/629,469	Filing Date 7/29/2003	Examiner Nguyen, Dilinh P.	Group Art Unit 2814
Invention: STRESS REDU AND/OR CHIP CARRIERS	JCTION IN FLIP-CHIP PBGA	PACKAGING BY UTILIZII	NG SEGMENTED CHIPS  OFF
I hereby certify that this	Requ	est for Reconsideration (9 pag	RECEIVED CENTRAL FAX CENTER AUG 2 4 2004
is being facsimile transmitte	ed to the United States Patent	(Identify type of correspondence) and Trademark Office (Fox	NA 703-877-0306
on <u>8/24/2004</u> ( <i>(Date</i> )		Kim Dwi (Typed of Prinled Nume of Pers (Signature) (Signature)	ion Signing Certificate)

## THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Darbha et al.

Art Unit: 2814

Scrial No.: 10/629,469

Dkt. No.: END920010115US2

Filed: 7/29/2003

Examiner: Nguyen, Dilinh P.

Title: STRESS REDUCTION IN FLIP-CHIP PBGA PACKAGING BY UTILIZING SEGMENTED CHIPS AND/OR CHIP CARRIERS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## Request for Reconsideration

Sir:

This Request for reconsideration is in response to the Final Office Action mailed June 28, 2004.